CLAIMS

[Claim1] A resin composition for a printed wiring board, comprising:

a maleimide compound having a maleimide group, a saturated or unsaturated divalent hydrocarbon group and a divalent group having at least two imido bonds;

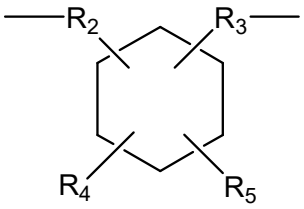
an aromatic maleimide compound different from the maleimide compound or a diamine compound;

a catalyst comprising at least one selected from the group consisting of an imidazole compound, a phosphorus compound, an azo compound and an organic peroxide; and

an organic filler,

wherein the hydrocarbon group is a group represented by the formula (II)

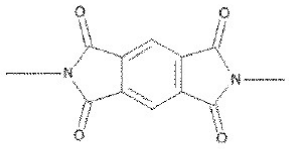
[Chemical Formula I]



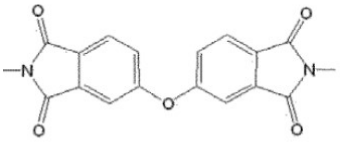
(II)

wherein in the formula (II), R_2 and R_3 each independently represent an alkylene group having 4 to 50 carbon atoms; R_4 represents an alkyl group having 4 to 50 carbon atoms; and R_5 represents an alkyl group having 2 to 50 carbon atoms, and

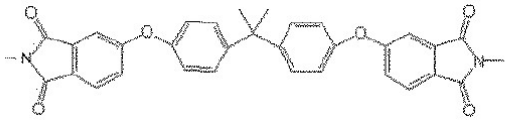
wherein the divalent group having at least two imido bonds is a group represented by the following formula (III), (IV), or (V):



(III)



(IV)



(V)

[Claim 2] The resin composition according to claim 1, wherein the catalyst comprises an organic peroxide.

[Claim 3] The resin composition according to claim 1 or 2, wherein a one-hour half-life temperature of the organic peroxide is 110 to 250°C.

[Claim 4] The resin composition according to any one of claims 1 to 3, wherein a content of the catalyst is 1 to 5 parts by mass with respect to 100 parts by mass of the maleimide compound.

[Claim 5] A prepreg for a printed wiring board, comprising the resin composition according to any one of claims 1 to 4 and a fiber base material.

[Claim 6] A resin film for a printed wiring board, formed by using the resin composition according to any one of claims 1 to 4.

[Claim 7] A laminate for a printed wiring board comprising:

a resin layer comprising a cured substance of the resin composition according to any one of claims 1 to 4; and

a conductor layer.

[Claim 8] A multilayer printed wiring board comprising:

a resin layer comprising a cured substance of the resin composition according to any one of claims 1 to 4; and

circuit layers.

[Claim 9] A method for producing a multilayer printed wiring board, comprising:

a step of laminating the resin film according to claim 6 on an inner layer circuit board to form a resin layer;

a step of heating and pressing the resin layer to cure the resin layer; and

a step of forming a circuit layer on the cured resin layer.